

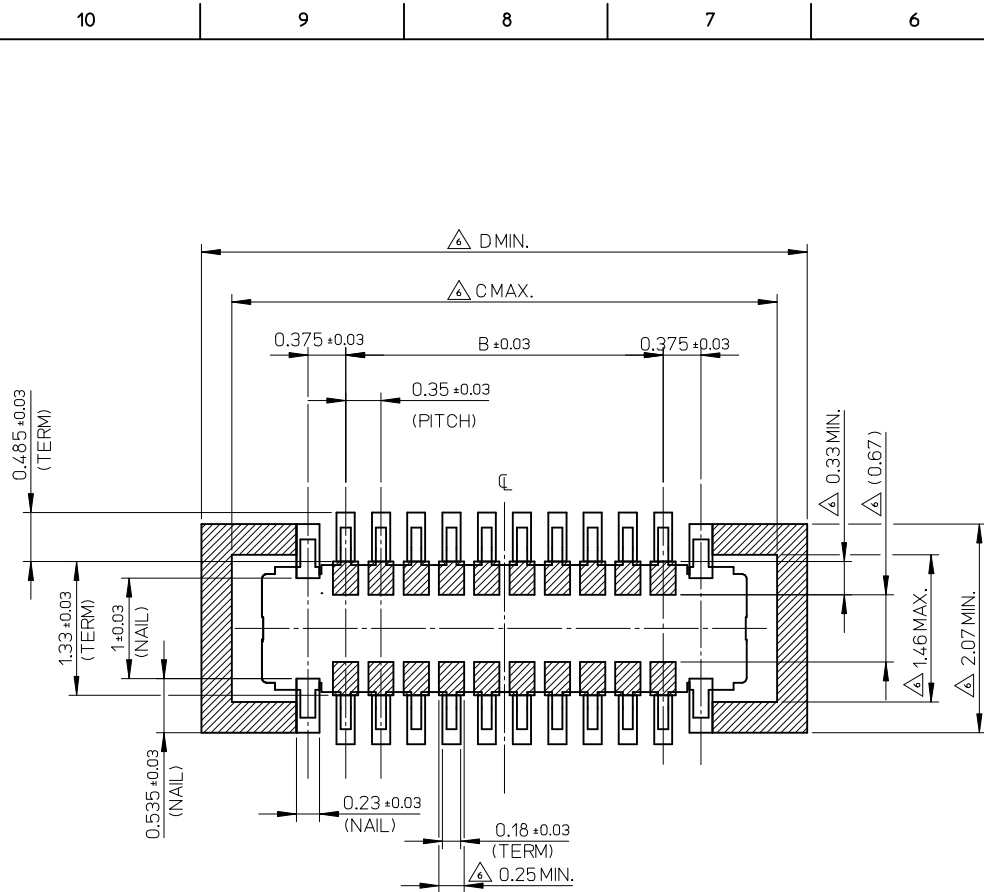
NOTES

1. MATERIAL  
 WAFER : LIQUID CRYSTAL POLYMER UL94V-0(COLOR : BLACK)  
 TERMINAL : COPPER ALLOY  
 FITTING NAIL : COPPER ALLOY
2. PLATING  
 TERMINAL :  
 GOLD / UNDER PLATING : NICKEL  
 \*DIVIDE INTO PARTS THE GOLD PLATING OF THE CONTACT AND THE TAIL PART BY THE NICKEL PLATING.
3. FITTING NAIL :  
 GOLD / UNDER PLATING : NICKEL  
 \*DIVIDE INTO PARTS THE GOLD PLATING OF THE CONTACT AND THE TAIL PART BY THE NICKEL PLATING.  
 \*EVEN THOUGH GOLD PLATING ON THE TOP SURFACE OF NAIL MIGHT BE THIN, NO FUNCTIONAL PROBLEM.
4. APPLY FOR (CIRCUIT/2)=EVEN.
5. MATE WITH : 505066-\*\*\*10
6. TAIL AND FITTING NAIL COPLANARITY TO BE 0.08MAXIMUM.
7. PROHIBITED AREA OF PATTERN WIRING AND SOLDER.  
 (FOR EACH AREA, THE WIRING THAT TOUCHES ON THE SOLDER CAN BE ATTACHED, THEN COVERED WITH A FILM TO KEEP SOLDER OUT.)
8. ELV and RoHS COMPLIANT.

3.56	2.96	0.70	2.36	505070-0610	0	---	6
D	C	B	A	EMBOSSED TAPE PACKAGE	HIGH VOL. TOOL	LOW VOL. TOOL	CIRCUIT
				ORDER NO.	SAMPLE PREPARATION O : TOOLED Δ : WORK IN PROCESS --- : TOOLING TO BE CONFIRMED		

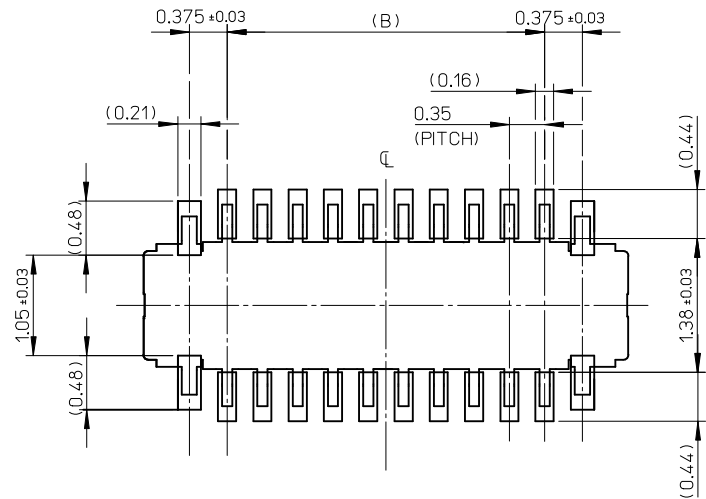
CONNECTOR SERIES No. : 505070-\*\*\*09

REVISED EC NO: J2016-1010 DRWN:MIT001 CHKD:TASAKAWA APPR:KMORIKAWA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER 0.5 UNDER	±0.05	KSASAKI	2014/04/15	0.35 BB CONN. H=0.6 SSB6 RP PLUG ASSY		
	0.5 OVER 1.0 UNDER	±0.1	CHECKED BY	DATE	<b>molex</b> DOCUMENT NO. SD-505070-001 SHEET NO. 1 OF 2		
1.0 OVER 30 UNDER	±0.2	KTANAKA03	2014/04/15				
30 OVER	±0.25	APPROVED BY	DATE	SEE CHART			
ANGULAR	±1 °	KMORIKAWA	2014/05/02	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3					



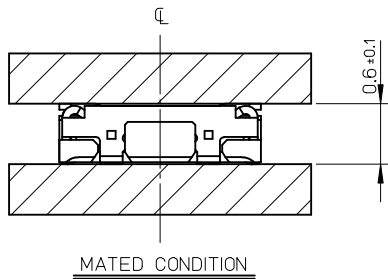
RECOMMENDED P.W.BOARD PATTERN LAYOUT (REFERENCE)

△ PROHIBITED AREA OF PATTERN WIRING AND SOLDER.  
(FOR EACH AREA, THE WIRING THAT TOUCHES ON THE SOLDER CAN BE ATTACHED, THEN COVERED WITH A FILM TO KEEP SOLDER OUT.)



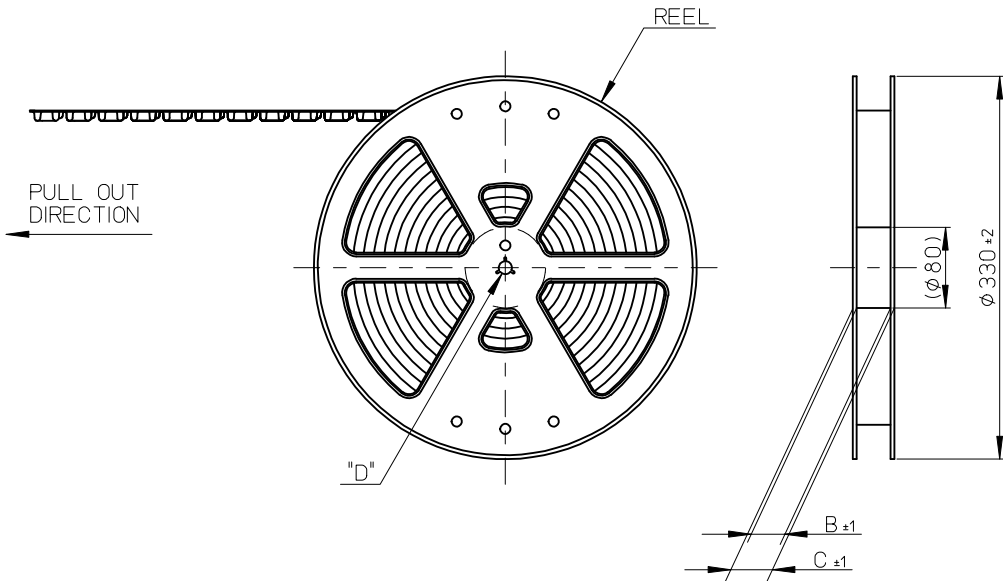
RECOMMENDED METAL MASK LAYOUT (REFERENCE)

RECOMMENDED THICKNESS OF METAL MASK : t=0.08mm  
RECOMMENDED OPEN APERTURE RATIO OF METAL MASK : 80%



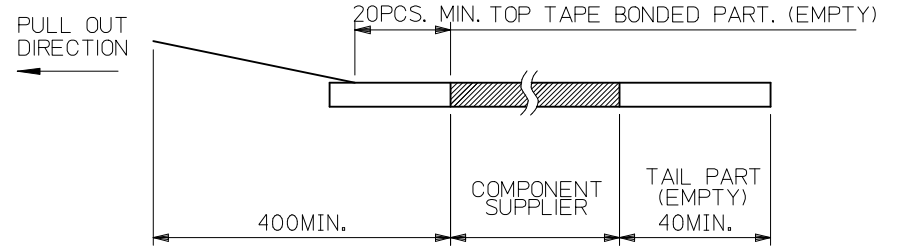
MATED CONDITION

<b>REVISED</b> EC NO: J2016-1010 DRWN: MIT001 CHKD: TASAKAWA APPR: KMORIKAWA	2016/03/30	2016/03/30	2016/03/31	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	0.25 UNDER	± 0.03	DRAWN BY KSASAKI		DATE 2014/04/15	TITLE 0.35 BB CONN. H=0.6 SSB6 RP PLUG ASSY					
	0.25 OVER	0.5 UNDER	± 0.05	CHECKED BY KTANAKA03		DATE 2014/04/15					
	0.5 OVER	1.0 UNDER	± 0.1	APPROVED BY KMORIKAWA		DATE 2014/05/02					
	1.0 OVER	10 UNDER	± 0.2	MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
10 OVER	30 UNDER	± 0.25	SEE SHEET1		SD-505070-001		2 OF 2				
30 OVER	± 0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

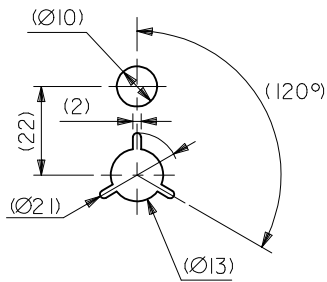


NOTES

1. RE DETAILED DIMENSION, SEE PRODUCT DRAWING.
2. NUMBER OF CONNECTORS : 3000PCS/REEL
3. LEAD TAPE LENGTH

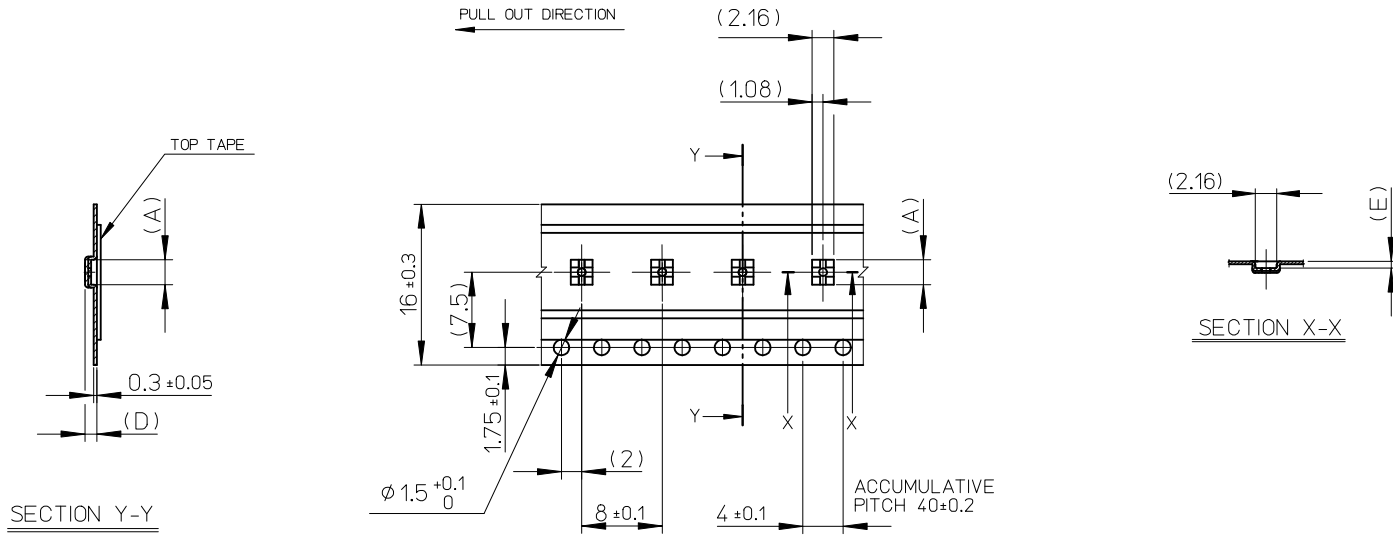


4. TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3.
5. MATERIAL  
 CARRIER TAPE : POLYSTYRENE  
 TOP TAPE : PET , OTHER  
 REEL : POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
6. ELV AND RoHS COMPLIANT



DETAIL "D"

REVISED EC NO: J2016-1010 DRWN:MITO01 2016/03/30 CHKD:TASAKAWA 2016/03/30 APPR:KMORIKAWA 2016/03/31	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		MODEL NO.	505066-**10	
	0.25 UNDER ±0.03		MM ONLY		DESIGN UNITS	METRIC	
	0.25 OVER 0.5 UNDER ±0.05		DRAWN BY DATE		0.35 BB CONN. H=0.6 SSB6 RP PLUG ASSY EMBSTP PKG <b>molex</b>		
	0.5 OVER 1.0 UNDER ±0.1		KSASAKI 2014/03/10				
	1.0 OVER 10 UNDER ±0.2		CHECKED BY DATE		THIRD ANGLE PROJECTION	TITLE	
	10 OVER 30 UNDER ±0.25		KTANAKA03 2014/03/10		SD-505070-002		
30 OVER ±0.3		APPROVED BY DATE		DOCUMENT NO.	SHEET NO.		
ANGULAR ±1 °		KMORIKAWA 2014/08/01		SEE CHART		1 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		SIZE A3					



16	0.66	1.16	21.4	17.4	2.43	505070-0610	0	---	6						
キャリアテープ幅 CARRIER TAPE WIDTH							(E)	(D)	C	B	(A)	MATERIAL No.	HIGH VOL. TOOL	LOW VOL. TOOL	CIRCUIT
											SAMPLE PREPARATION				

REVISED EC NO: J2016-1010 DRWN: IT001 CHKD: TASAKAWA APPR: KMORIKAWA	GENERAL TOLERANCES (UNLESS SPECIFIED)				DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	0.25 UNDER				± 0.03	DRAWN BY KSASAKI	DATE 2014/03/10	TITLE 0.35 BB CONN. H=0.6 SSB6 RP PLUG ASSY EMBSTP PKG			
	0.25 OVER	0.5	UNDER			± 0.05	CHECKED BY KTANAKA03	DATE 2014/03/10	molex		
	0.5 OVER	1.0	UNDER			± 0.1	APPROVED BY KMORIKAWA	DATE 2014/08/01			
	1.0 OVER	10	UNDER			± 0.2	MATERIAL NO.		DOCUMENT NO.	SHEET NO.	
10 OVER	30	UNDER			± 0.25	SEE CHART		SD-505070-002	2 OF 2		
30 OVER					± 0.3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
ANGULAR				± 1 °							
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS											